

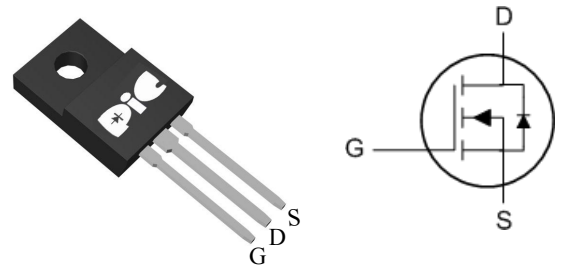
➤ General Description

This PAN00TF16GF N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent $R_{ds(On)}$ performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

➤ Feature

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent C_{dv}/dt effect decline
- Advanced high cell density Trenchtechnology

➤ TO220F



➤ Application

- SMPS Power Supplier
- Charger Adapter
- Power Tools
- LED Lighting

➤ Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current, V_{GS} @ 10V ₁	$I_D@T_C=25^\circ C$	17.5	A
Continuous Drain Current, V_{GS} @ 10V ₁	$I_D@T_C=100^\circ C$	11	A
Continuous Drain Current, V_{GS} @ 10V ₁	$I_D@T_A=25^\circ C$	4.2	A
Continuous Drain Current, V_{GS} @ 10V ₁	$I_D@T_A=70^\circ C$	3.4	A
Pulsed Drain Current ₂	I_{DM}	54	A
Single Pulse Avalanche Energy ₃	EAS	36.5	mJ
Avalanche Current	I_{AS}	27	A
Total Power Dissipation ₄	$P_D@T_C=25^\circ C$	34.7	W
Total Power Dissipation ₄	$P_D@T_A=25^\circ C$	2	W
Storage Temperature Range	T_{STG}	-55 to 150	$^\circ C$
Operating Junction Temperature Range	T_J	-55 to 150	$^\circ C$
Thermal Resistance Junction-ambient ₁	$R_{\theta JA}$	62	$^\circ C/W$
Thermal Resistance Junction-Case ₁	$R_{\theta JC}$	3.6	$^\circ C/W$

➤ Electrical Characteristics ($T_J=25^\circ C$ Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	100	---	---	V
BVDSS Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^\circ C, I_D=1mA$	---	0.098	---	$V/^\circ C$
Static Drain-Source On-Resistance ²	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	---	---	47	m Ω
		$V_{GS}=4.5V, I_D=15A$	---	---	50	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.0	---	2.5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		---	-5.52	---	$mV/^\circ C$
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=80V, V_{GS}=0V, T_J=25^\circ C$	---	---	10	μA
		$V_{DS}=80V, V_{GS}=0V, T_J=55^\circ C$	---	---	100	
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
Forward Transconductance	g_{fs}	$V_{DS}=5V, I_D=15A$	---	31	---	S
Gate Resistance	R_g	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	1.6	---	Ω
Total Gate Charge (10V)	Q_g	$V_{DS}=80V, V_{GS}=10V, I_D=15A$	---	61	---	nC
Gate-Source Charge	Q_{gs}		---	9	---	
Gate-Drain Charge	Q_{gd}		---	10.3	---	
Turn-On Delay Time	$T_{d(on)}$	$V_{DD}=50V, V_{GS}=10V, R_G=3.3\Omega, I_D=15A$	---	10.8	---	ns
Rise Time	T_r		---	48	---	
Turn-Off Delay Time	$T_{d(off)}$		---	52	---	
Fall Time	T_f		---	9.6	---	
Input Capacitance	C_{iss}	$V_{DS}=15V, V_{GS}=0V, f=1MHz$	---	3848	---	pF
Output Capacitance	C_{oss}		---	137	---	
Reverse Transfer Capacitance	C_{rss}		---	82	---	

➤ Diode Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current ^{1,5}	I_S	$V_G=V_D=0V, \text{ Force Current}$	---	---	17.5	A
Pulsed Source Current ^{2,5}	I_{SM}		---	---	54	A
Diode Forward Voltage ²	V_{SD}	$V_{GS}=0V, I_S=1A, T_J=25^\circ C$	---	---	1.2	V
Reverse Recovery Time	t_{rr}	$I_F=15A, di/dt=100A/\mu s, T_J=25^\circ C$	---	29	---	nS
Reverse Recovery Charge	Q_{rr}		---	40	---	nC

Note :

1. Pulse width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=27A$
4. Ensure that the channel temperature does not exceed $150^\circ C$.
5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

➤ Typical Characteristics

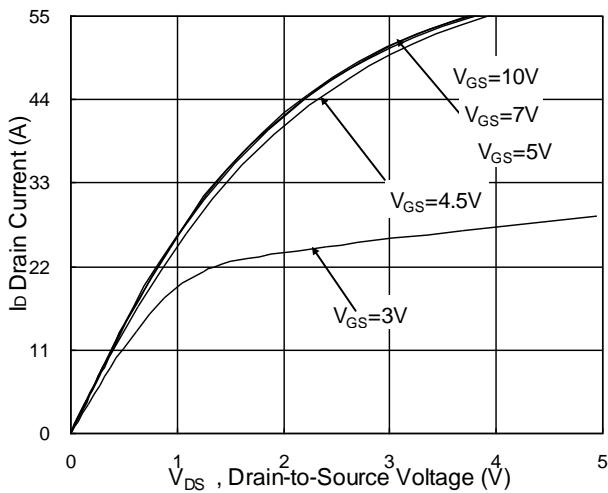


Fig.1 Typical Output Characteristics

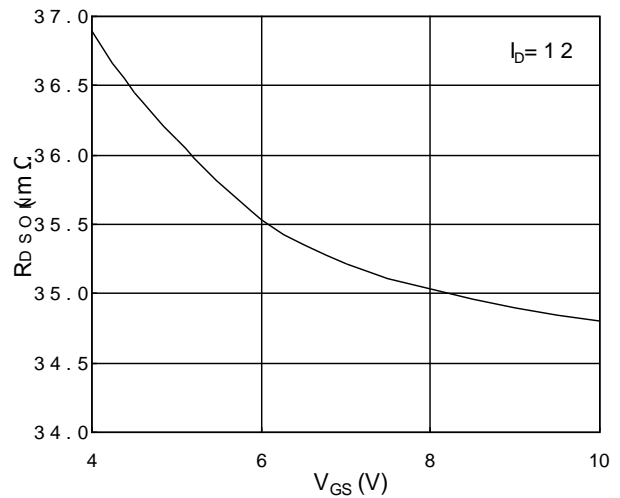


Fig.2 On-Resistance vs. Gate-Source

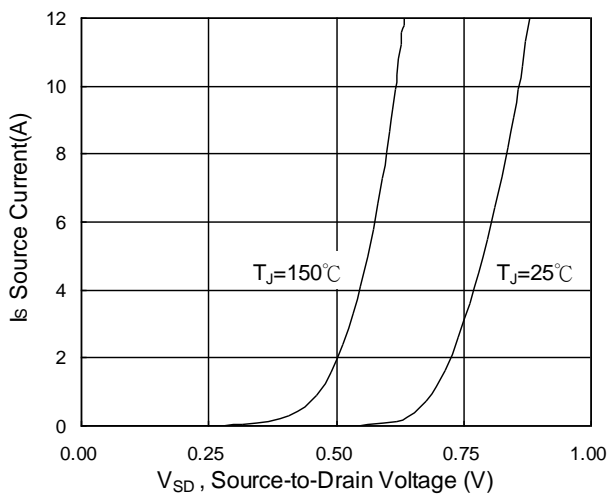


Fig.3 Forward Characteristics Of Reverse

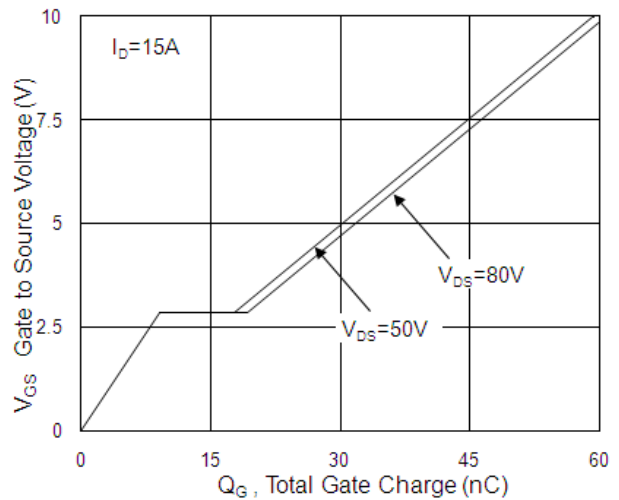


Fig.4 Gate-Charge Characteristics

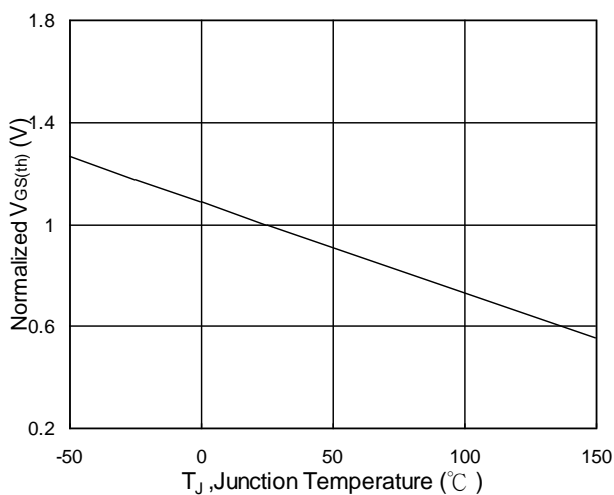


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

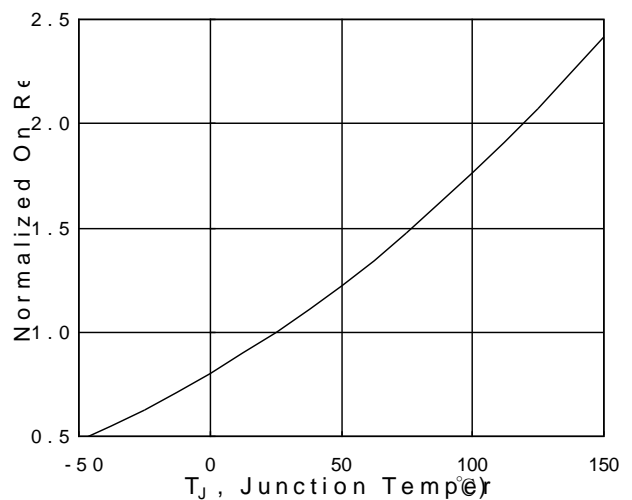


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

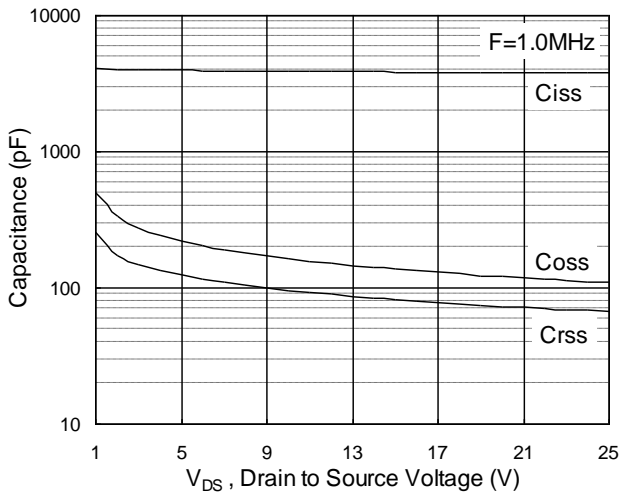


Fig.7 Capacitance

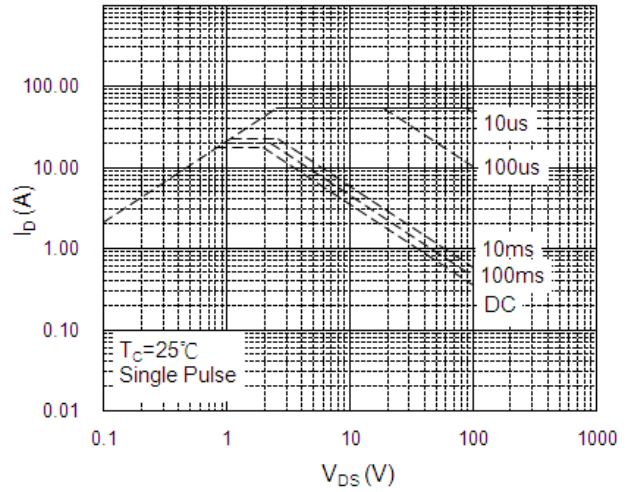


Fig.8 Safe Operating Area

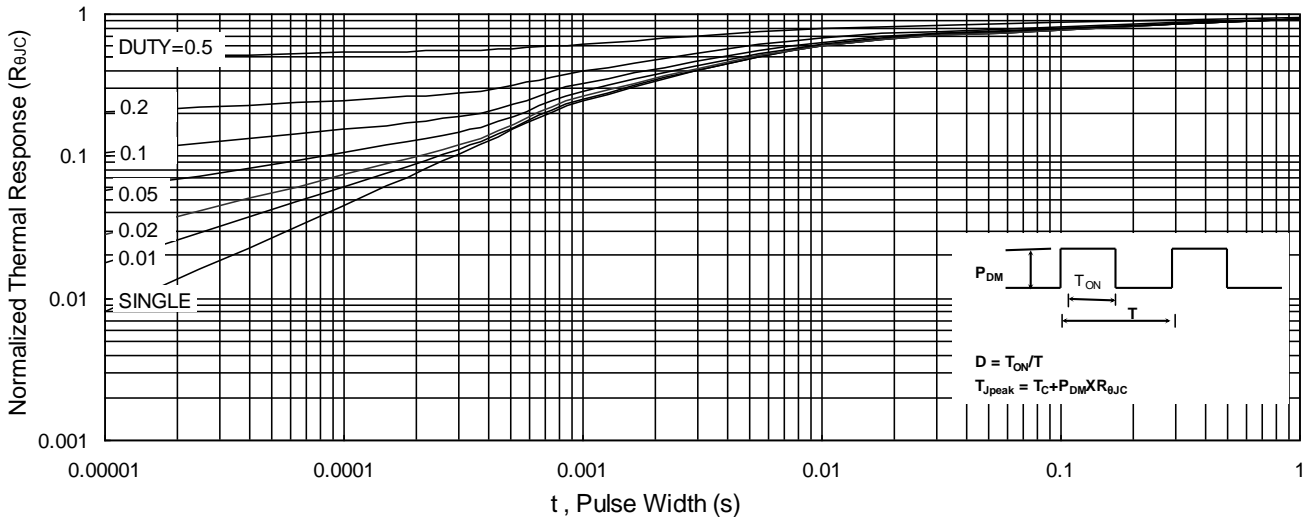


Fig.9 Normalized Maximum Transient Thermal Impedance

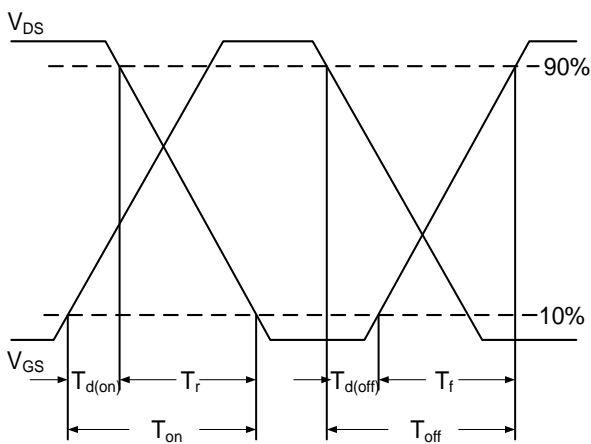


Fig.10 Switching Time Waveform

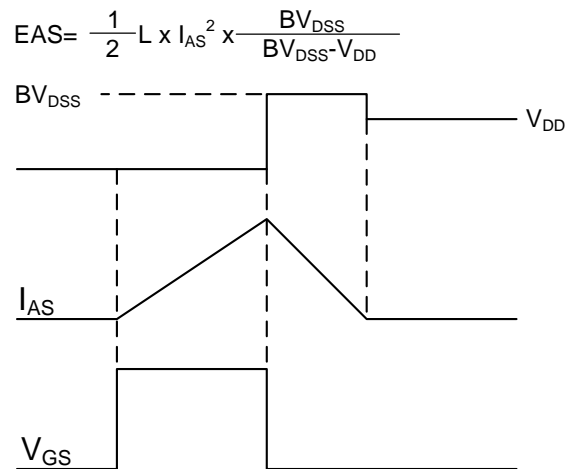


Fig.11 Unclamped Inductive Switching Waveform

➤ Recommand IR Reflow Soldering Thermal Profile

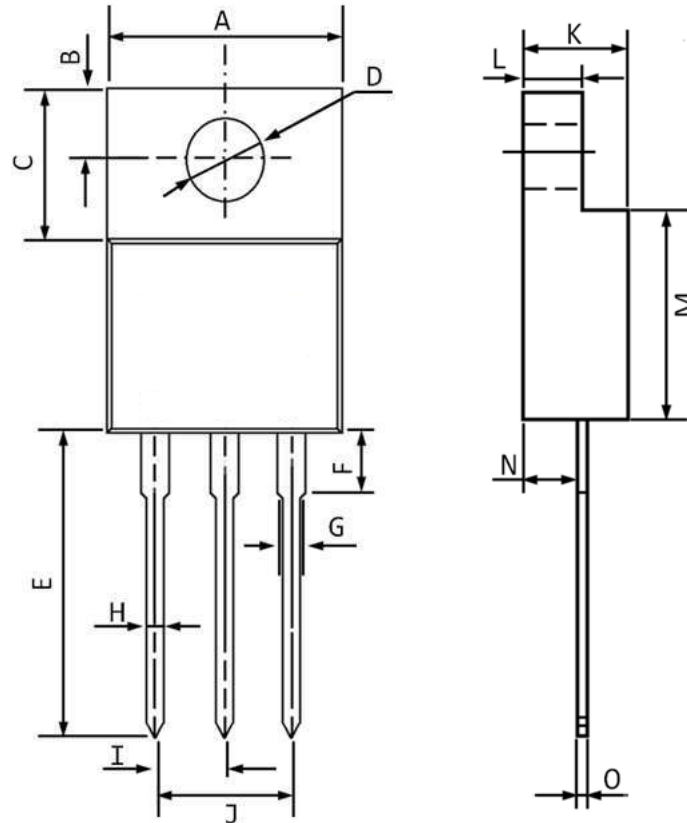


Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T_{smin})	150°C
Temperature Max. (T_{smax})	200°C
Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds
Average Ramp-up Rate (t_L to t_P)	3°C/second max.
Liquidous Temperature (T_L)	217°C
Time (t_L) Maintained Above (T_L)	60 – 150 seconds
Peak Temperature	260°C +0°C / -5°C
Time (t_P) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (T_P to T_L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

➤ Ordering Information

Part Number	Description	Quantity
PAN00TF16GF	TO-220F / 50 pcs/tube	1000 pcs

➤ Package Information (TO-220F)



SYMBOLS	MILLIMETERS		INCHES	
	Min.	Max.	Min.	Max.
A	—	10.50	—	0.414
B	2.60	3.00	0.102	0.118
C	6.70	7.10	0.264	0.280
D	2.90	3.50	0.114	0.138
E	13.10	13.90	0.516	0.548
F	—	4.00	—	0.158
G	1.11	1.45	0.044	0.057
H	0.40	0.80	0.016	0.032
I	2.40	2.80	0.095	0.110
J	5.00	5.40	0.197	0.213
K	4.30	4.70	0.169	0.185
L	2.90	3.30	0.114	0.130
M	8.20	9.00	0.323	0.355
N	2.50	2.90	0.099	0.114
O	0.40	0.80	0.016	0.032

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